

## INITIAL INFORMATION DATA SHEET

### APPLICATION INFORMATION

Application Type:: Regular  
Subject Matter:: Utility  
Title:: High Performance FlipChip Package  
That Incorporates Heat Removal With  
Minimal Thermal Mismatch  
Docket Number:: X-901 US  
Request for Early Pub?:: No  
Request for Non-Pub?:: Yes  
Total Drawing Sheets:: 3  
Small Entity?:: No

### INVENTOR INFORMATION

Inventor Authority Type:: Inventor  
Primary Citizenship Ctry:: US  
Given Name:: Abu K.  
Family Name:: Eghan  
Street:: 6572 Springpath Lane  
City:: San Jose  
State or Province:: CA  
Postal or Zip Code:: 95124-4549

Inventor Authority Type:: Inventor  
Primary Citizenship Ctry:: US  
Given Name:: Lan H.  
Family Name:: Hoang  
Street:: 38848 Bell Street  
City:: Fremont  
State or Province:: CA  
Postal or Zip Code:: 94586

**CORRESPONDENCE INFORMATION**

Correspondence Customer Number:: 24309

**REPRESENTATIVE INFORMATION**

Representative Customer Number::	24309	
----------------------------------	-------	--

**ASSIGNEE INFORMATION**

Assignee Name:: Xilinx, Inc.  
Street:: 2100 Logic Drive  
City:: San Jose  
State or Province:: California  
Postal or Zip Code:: 95124